## APPENDIX A

## VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

A marked-up version of each of the presently amended claims, highlighting the changes thereto, follows:

2. (Twice Amended) The IC package of claim 1, wherein the package body [is] includes one of [selected from a group consisting of] a transfer molded plastic package body and a preformed ceramic package body.

3. (Twice Amended) The IC package of claim 1, wherein the IC die [is] includes one of [selected from a group consisting of] a Dynamic Random Access Memory (DRAM) IC die, a Static Random Access Memory (SRAM) IC die, a Synchronous DRAM (SDRAM) IC die, a Sequential Graphics Random Access Memory (SGRAM) IC die, a flash Electrically Erasable Programmable Read-Only Memory (EEPROM) IC die, and a processor IC die.

4. (Twice Amended) The IC package of claim 1, wherein the lead frame includes one of [is selected from a group consisting of] a peripheral-lead finger lead frame, a Leads Over Chip (LOC) lead frame, and a Leads Under Chip (LUC) lead frame.

27. (Twice Amended) The IC package of claim 26, wherein the package body includes one of [is selected from a group consisting of] a transfer molded plastic package body and a preformed ceramic package body.

28. (Twice Amended) The IC package of claim 25, wherein the IC die includes one of [is selected from a group consisting of] a Dynamic Random Access Memory (DRAM) IC die, a Static Random Access Memory (SRAM) IC die, a Synchronous DRAM (SDRAM) IC die, a

Sequential Graphics Random Access Memory (SGRAM) IC die, a flash Electrically Erasable Programmable Read-Only Memory (EEPROM) IC die, and a processor IC die.

29. (Twice Amended) The IC package of claim 25, wherein the lead frame includes one of [is selected from a group consisting of comprising] a peripheral-lead finger lead frame, a Leads Over Chip (LOC) lead frame, and a Leads Under Chip (LUC) lead frame.